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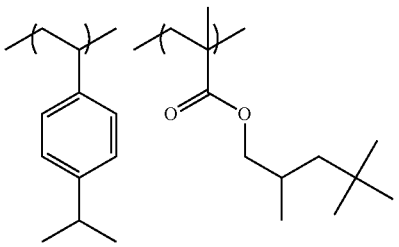
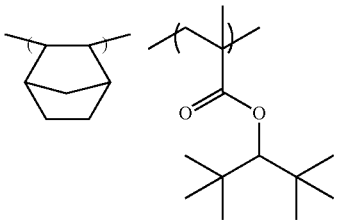
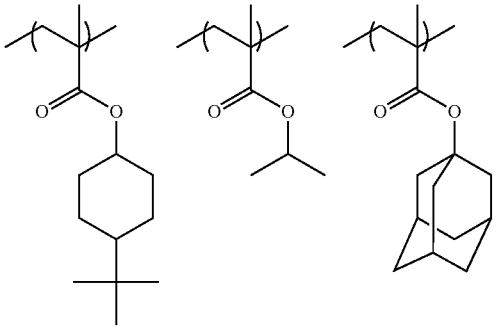
(C-23)



(C-24)



(C-25)



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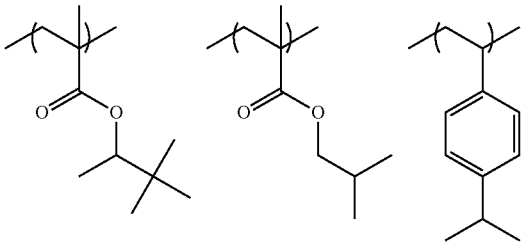

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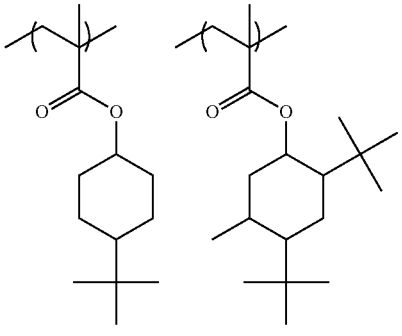

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(C-28)

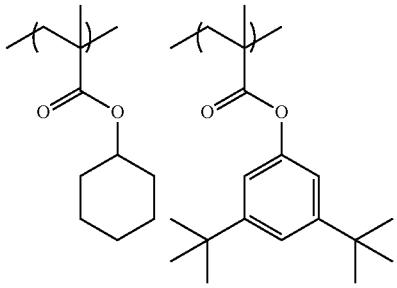

TABLE 2

Resin	Composition	Mw	Mw/Mn
C-1	50/50	9600	1.74
C-2	60/40	34500	1.43
C-3	30/70	19300	1.69
C-4	90/10	26400	1.41
C-5	100	27600	1.87
C-6	80/20	4400	1.96
C-7	100	16300	1.83
C-8	5/95	24500	1.79
C-9	20/80	15400	1.68
C-10	50/50	23800	1.46
C-11	100	22400	1.57
C-12	10/90	21600	1.52
C-13	100	28400	1.58
C-14	50/50	16700	1.82
C-15	100	23400	1.73
C-16	60/40	18600	1.44
C-17	80/20	12300	1.78
C-18	40/60	18400	1.58
C-19	70/30	12400	1.49
C-20	50/50	23500	1.94
C-21	10/90	7600	1.75
C-22	5/95	14100	1.39
C-23	50/50	17900	1.61
C-24	10/90	24600	1.72
C-25	50/40/10	23500	1.65
C-26	60/30/10	13100	1.51
C-27	50/50	21200	1.84
C-28	10/90	19500	1.66

[0466] <Acid Diffusion Control Agent (D)>

[0467] The composition of the present invention preferably contains an acid diffusion control agent (D). The acid diffusion control agent (D) acts as a quencher that traps acids generated from the acid generator or the like upon exposure and inhibits a reaction of the acid-decomposable resin in the unexposed area by extra generated acids. As the acid diffusion control agent (D), a basic compound, a low-molecular compound which has a nitrogen atom and a group capable of leaving by the action of an acid, a basic compound whose basicity is reduced or lost upon irradiation with active light or radiation, or an onium salt which becomes a relatively weak acid with respect to the acid generator can be used.

[0468] Preferred examples of the basic compound include compounds having structures represented by the following Formulae (A) to (E).

(A)